



M82200-9/UM PECVD



Overview

M82200-9/UM PECVD utilizes direct plasma deposition process to grow high quality anti-reflection coating on the surface of solar cell. It is one of the tube film coating devices with the largest per stack capacity.

Benefits



Excellent film uniformity: within wafer $\leq \pm 3\%$, wafer to wafer $\leq \pm 3\%$ and run to run $\leq \pm 2\%$.



300–600°C temperature control range to meet the process requirements of film coating and wafer annealing.



420mm quartz tube to achieve 1800 pcs/h throughput (4 stacks, 308 pcs/stack/run).



N₂O (laughing gas) pipeline and operation software reserved for anti-PID process.



Full-automatic loading and unloading system, onekey process control and complete alarm and protection function.

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Specification

Process Performance	Film uniformity: within wafer $\leq \pm 3\%$, wafer to wafer $\leq \pm 3\%$, run to run $\leq \pm 2\%$ Refractive index uniformity: $\leq \pm 0.02$
Throughput	308 pcs/stack, ≥ 1800 pcs/h (4-stack)
Temperature Control	Flat temperature zone: 1370 mm Method: 5-section cascade control with internal and external thermocouples Range: 300 – 600 °C Precision: $\leq \pm 2$ °C/1250 mm Stability: $\leq \pm 2$ °C/4 h (at 450 °C)
Pressure Control	Range: 1600 mTorr, ± 300 mTorr adjustable Ultimate vacuum: ≤ 1 Pa Air leakage rate: ≤ 1 Pa/min after pump stopped and valve closed Vacuum recovery speed: AP \rightarrow 30 mTorr ≤ 2 min
Boat Conveyor	Double SiC stainless steel or cantilever bar boat conveyor, with continuously adjustable transfer speed of 0 – 3500 mm/min Positioning precision: $\leq \pm 0.5$ mm Max load: ≥ 25 kg
Gas Piping System	4 pipelines with MFC control, precision $\leq \pm 1\%$ F.S, leakage rate $\leq 10^{-7}$ Pa.m ³ /s
Interlock	Furnace door conditions; air pressure, N ₂ pressure, water flow pressure and process; special gas valves
System Dimension	10070 mm x 1960 mm x 3070 mm (L x W x H, including vacuum pump)
Power	Peak power: ≤ 280 KVA, heat preservation: ≤ 100 KVA (4-stack)
Uptime	$\geq 97\%$
Control Method	Automatic process control and real-time process parameter and procedure monitoring, with fault diagnosis, alarm and protection functions.
Alarm and Safety	Voice and light indicator for process status; alarm for computer fault and over-temperature; alarm and protection for under-temperature, MFC deviation, reaction chamber pressure deviation and ultimate temperature

Configuration

Vacuum Pump	Alcatel ADS602H	 阿尔卡特	Mass flow meter	HORIBA	
	Edwards		Diaphragm Gauge	INFICON	
RF Power	AE PE2-10KW		Industrial PC	Advantech	 研華科技
	TRUMPF				
Temperature Controller	Azbil		PLC	Mitsubishi	 Changes for the Better